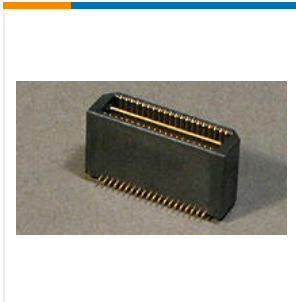




BOARD-TO-BOARD HEADERS & RECEPTACLES



TE CONNECTIVITY (TE)

MSB0.80PL11ASY040FL,GP,10,-TR

MICTOR | GP , MICTOR SB

6-1658015-1

TE Internal Number: 6-1658015-1

Always EU RoHS/ELV Compliant

Connector Style **Plug**

Centerline **.8 mm [.031 in]**

Stack Height **11 mm [.433 in]**

Number of Positions **40**

Packaging Method **Pocket Tape**

Active

PRODUCT DRAWING
English

3D PDF

Product Drawings

[HEADER ASSEMBLY, 11.0MM \[.433\] VERTICAL, 0.80MM CL, MICTOR SB](#)

PDF (TIFF AVAILABLE)
English

[HEADER ASSEMBLY, 11.0MM \[.433\] VERTICAL, 0.80MM CL, MICTOR SB](#)

PDF (TIFF AVAILABLE)
English

CAD Files

[3D PDF](#)

PDF
English

[Customer View Model](#)

2D_DXF.ZIP
English

[Customer View Model](#)

3D_IGS.ZIP
English

[Customer View Model](#)

3D_STP.ZIP
English

Catalog Pages/Data Sheets

[MICTOR SB Interconnection System](#)

PDF
English

Product Specifications

Product Specification

[MICTOR SB \(True SMT\) Connector](#)

PDF
English

Application Specification

[MICTOR SB Vertical Connectors For Surface Mount Technology \(SMT\) Printed Circuit \(PC\) Board Applications](#)

PDF
English

Qualification Test Report

[MICTOR SB \(True SMT\) Connector](#)

PDF
English

Please review product documents or [contact us](#) for the latest agency approval information. Please Note: Use the Product Drawing for all design activity.

Product Type Features	Connector Style	Plug
	PCB Mounting Orientation	Vertical
	Row-to-Row Spacing	4.73 mm [.185889 in]
	Product Type	Connector
	Applies To	Printed Circuit Board
	Boss	With
	Series	MICTOR SB
	Connector System	Board-to-Board
Connector Type	Connector Assembly	

Configuration Features	Number of Positions	40
	Number of Rows	2
	Selectively Loaded	Fully Loaded
	Stackable	No

Electrical Characteristics	Voltage (VAC)	125
	Impedance	50 Ω
	Insulation Resistance (M Ω)	5000
	Dielectric Withstanding Voltage (VAC)	675

Body Features	Polyamide Film Pad	With
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Contact Features	Contact Mating Area Plating Material	Select Gold
	Contact Mating Area Plating Thickness	.25 μm [9.8425 μin]
	Signal Contact Material	Phosphor Bronze
	Contact Shape	Square
	Contact Current Rating (A)	1.25, 9.5
	Contact Type	Pin
	Ground Contact Material	Phosphor Bronze
	Contact Configuration	Single Beam
	Solder Tail Contact Plating Material	Gold over Nickel
	Solder Tail Contact Plating Thickness	.25 μm [9.8425 μin]
	Contact Base Material	Phosphor Bronze

Termination Features	Termination Method to PC Board	Surface Mount
Mechanical Attachment	Mating Alignment Type	Guide Post
	PCB Mount Retention	Without
	PCB Mount Alignment Type	Locating Posts
Housing Features	Centerline	.8 mm [.031 in]
	Housing Material	LCP (Liquid Crystal Polymer)
	Housing Color	Black
Dimensions	Stack Height	11 mm [.433 in]
	Height	10.06 mm [.395358 in]
Usage Conditions	Operating Temperature Range	-65 – 125 °C [-85 – 257 °F]
Operation/Application	Pick and Place Cover	Without
	Assembly Process Feature	None
	For Use With	Receptacle Assembly
Packaging Features	Packaging Method	Pocket Tape
	Packaging Quantity	300
Other	Comment	Use of stand offs recommended. Contact Product Engineering for recommendations.
Product Compliance	Statement of Compliance PDF VIEW ALL PRODUCT COMPLIANCE	